Product Overview

SK-AM62P-LP Design Package Folder and Files List

Table 1 lists names of the folders and file names in the folders along with the format for all the files that have been included in the SK-AM62P-LP. SK-AM62P-LP starter kit (SK) evaluation module (SKEVM) is built around our AM62P display processor, (17mm x 17mm, 0.65-/0.8mm pitch with VCA, 466-pin FCBGA), which includes scalable Arm® Cortex®-A53 performance and embedded features, such as triple high-definition display support, high-performance 3D-GPU, and 4K video acceleration. The product overview document is available on SK-AM62P-LP product folder on TI.com for customers to review before downloading the single zip folder.

Table 1. Proc164E1.1

Folder (1st level)	Folder (2nd level)	Files	File type
----	----	Proc164E1.1_Folders_Files_List	XLS
1_SCHEMATIC	PDF	PROC164E1-1_SCH_With_Design-Updates..Notes_V1.0	PDF
	PDF -Backup_SK_Schematic	PROC164E1-1_SCH	PDF
	----	Proc164E1-1_Schematic_Revision_Readme	DOC
	ORCAD	PROC164E1-1_SCH_With_Design-Updates..Notes_V1.0	DSN
	ORCAD - Backup_SK_Schematic	PROC164E1-1_SCH	DSN
2_BOM	----	PROC164E1-1_BOM_With_Design_Updates..Notes_V1.0	XLS
	Backup_SK_Schematic_BOM	PROC164E1-1_BOM	XLS
3_Board_File	Allegro	PROC164E1-1_BRD	BRD
	Simulation Scorecard	AM62x_Simulations_Scorecard	PDF
	Altium_ASCII	PROC164E1-1_BRD	ALG
4_Gerber	ODBGBR	PROC164E1-1_ODBGBR	ZIP
	274X	PROC164E1-1_274XGBR	ZIP
	IPC-D-356_NETLIST	PROC164E1-1_IPC	IPC
5_Gerber_PDF	FAB	PROC164E1-1_FAB	PDF
	PCB LAYERS	PROC164E1-1_ALL_LAYER	PDF
	Geber Layers	PROC164E1-1_ALL_LAYER	PDF
6_Assembly_Models_Package	2D	PROC164E1-1_DXF_BASY	DXF
		PROC164E1-1_DXF_TASY	DXF
	3D	PROC164E1-1_3D.STEP	STP
	IDF	PROC164E1-1_BRD	EMP
		PROC164E1-1_BRD	EMN
	Assembly_Drawing	PROC164E1-1 ASSEMBLY	PDF
		PROC164E1-1_TASY	PDF
		PROC164E1-1_BASY	PDF
	STNL	art_aper + 8 x .ART files	ART
	XY-REP	PROC164E1-1_XY-REP	XLS
7_PCB_LAYER_STACKUP	---	AM62P SKEVM_STACKUP-12L-2-5-2023[0592]	PDF
8_Power_Supply_Sequencing	---	Proc164E1.1_SK-AM62P_LP_Power Sequence_RevE1.1	PDF

References

- Texas Instruments, *[FAQ] AM62P / AM62P-Q1 - Custom board hardware design - Design and Review notes for Reuse of SK-AM62P-LP Schematics* article

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